Amendments to the Claims:

Please cancel claim 14 and amend claims 1, 4-7 and 9-12 as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended). A sample assembly for a thermoelectric analyzer comprising:

(a) an electrically-insulating substrate having a longitudinally-central region and two longitudinally-end regions;

(b) an adhesive layer disposed on said longitudinally-central region and made of a material selected from a group consisting of indium and gold-tin alloy ~~a pair of junction electrode layers non-contiguously formed on said substrate~~;

(c) a pair of junction electrode layers formed on said two longitudinally-end regions respectively with certain distances from ~~an adhesive layer disposed on said substrate,~~ said adhesive layer ~~being non-contiguous with said pair of junction electrode layers~~;

(d) a sample fixed to said adhesive layer, said sample ~~and~~ being ~~non-contiguous with said pair of junction electrode layers~~

for thermostatic analysis in which an electric property of said sample is measured as a temperature of said sample varies;

(e) a pair of electrode layers formed on a top surface of said sample; ~~and~~

(f) ~~two electrically-conductive wires,~~ a first electrically-conductive wire connecting one of said electrode layers with one of said junction electrode layers~~,~~ ; and

(g) a second electrically-conductive wire connecting the other of said electrode layers with the other of said junction electrode layers wherein an electrical property of the sample is measured as a temperature of the sample varies.

Claim 2 (Original). A sample assembly according to claim 1, wherein said adhesive layer is made of indium.

Claim 3 (Original). A sample assembly according to claim 2, wherein said substrate is made of a material selected from a group consisting of aluminum nitride, boron nitride, beryllium oxide and aluminum oxide.

Claim 4 (Currently Amended). A sample assembly according to claim 3, wherein each of said ~~pair of~~ electrode layers and said

~~pair of~~ junction electrode layers is ~~made of~~ a multilayer including a top layer which is a gold layer, and said first and second electrically-conductive wires are gold wires.

Claim 5 (Currently Amended). A sample assembly according to claim 4, wherein said pair of electrode layers, said pair of junction electrode layers and said first and second electrically-conductive ~~wire means~~ wires are arranged mirror-symmetrical with respect to a center of said sample.

Claim 6 (Currently Amended). A sample assembly according to claim 5, wherein said sample is a compound semiconductor.

Claim 7 (Currently Amended). A sample assembly according to claim 1, wherein said adhesive layer is made of a gold-tin alloy.

Claim 8 (Original). A sample assembly according to claim 1, wherein said substrate is made of a material selected from a group consisting of aluminum nitride, boron nitride, beryllium oxide and aluminum oxide.

Claim 9 (Currently Amended). A sample assembly according to claim 1, wherein said sample assembly is adapted to be supported

by two support rods which also serve ~~also~~ as conductors for an electric circuit, and wherein gold washers are inserted between said support rods and said junction electrode layers.

Claim 10 (Currently Amended). A sample assembly according to claim 1, wherein each of said electrode layers and said junction electrode layers is ~~made of~~ a multilayer including a top layer which is a gold layer, and said first and second electrically-conductive ~~wire means~~ wires are gold wires.

Claim 11 (Currently Amended). A sample assembly according to claim 1, wherein said pair of electrode layers, said pair of junction electrode layers and said first and second electrically-conductive wires ~~wire means~~ are arranged mirror-symmetrical with respect to a center of said sample.

Claim 12 (Currently Amended). A sample assembly according to claim 1, wherein said sample is a compound semiconductor.

Claim 13 (Original). A sample assembly according to claim 1, wherein said sample has a plane size of 5 mm x 5 mm or less.

Claim 14 (Cancelled).

Amendments to the Drawings:

The attached sheets of drawings include changes to Fig. 5. Specifically, attached hereto is an annotated sheet showing changes to Fig. 5 and a replacement sheet for Fig. 5 which includes the changes thereto. The changes to Fig. 5 are directed to a portion which was previously not translated from Japanese into English at the time the present application was filed. The amendment of Fig. 5 is supported by the application as originally filed (see page 15, lines 17-21 of the present application).

Attachments: Marked sheet showing changes to Fig. 5
Replacement sheet for Fig. 5